

Title (en)
PTC DEVICE AND METHOD FOR PRODUCING THE SAME

Title (de)
PTC-BAUTEIL UND HERSTELLUNGSVERFAHREN

Title (fr)
DISPOSITIF A COEFFICIENT DE TEMPERATURE POSITIF ET SON PROCEDE DE FABRICATION

Publication
EP 1126478 A4 20020109 (EN)

Application
EP 00946362 A 20000714

Priority
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Abstract (en)
[origin: EP1126478A1] On the surface of formed composition material (12) in which a conductive powder filler is blended and kneaded with a crystalline polymer by 35 to 60 volume percent, conductive material (13) is pressure sealed and buried so that part of the conductive material is exposed, and plated electrodes (14A) and (14B) are formed by plating treatment on formed composition material (12) with partly exposed conductive material (13). And at least one out of TiC, WC, W₂C, ZrC, VC, NbC, TaC, and Mo₂C is used as conductive powder filler. The adhesion between the PTC composition material and the electrodes becomes good, and it becomes possible to reduce contact resistance value between the two. Further a PTC element with excellent stability to repeated turning on electricity can be obtained. <IMAGE>

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IPC 8 full level
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• [A] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 07 31 July 1997 (1997-07-31)
• [A] PATENT ABSTRACTS OF JAPAN vol. 1998, no. 13 30 November 1998 (1998-11-30)
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